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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHIA-JUNG HSU	09/16/2020
CHIN-HUNG CHEN	09/16/2020
CHUN-YA CHIU	09/16/2020
CHIH-KAI HSU	09/16/2020
SSU-I FU	09/16/2020
TSAI-YU WEN	09/16/2020
SHI YOU LIU	09/16/2020
YU-HSIANG LIN	09/16/2020

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17026062

CORRESPONDENCE DATA

Fax Number: (949)660-0809

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 949-660-0761

Email: jcpatents@gmail.com

Correspondent Name: J C PATENTS

Address Line 1:4 VENTURE, SUITE 250Address Line 4:IRVINE, CALIFORNIA 92618

ATTORNEY DOCKET NUMBER:	JCLA102883
NAME OF SUBMITTER:	JIAWEI HUANG
SIGNATURE:	/JIAWEI HUANG/
DATE SIGNED:	09/18/2020

PATENT REEL: 053823 FRAME: 0238

	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 10	
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PATENT REEL: 053823 FRAME: 0239

the application.

DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION Declaration Submitted With Initial Filing OR Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required) (Title of the Invention) STRUCTURE OF SEMICONDUCTOR DEVICE AND METHOD FOR **FABRICATING THE SAME** As a below named inventor (hereinafter designated as the undersigned), I hereby declare that: This declaration is directed to: The attached application, OR United States Application Number or PCT International application number _Filed on _____ The above-identified application was made or authorized to be made by me. I believe I am the original inventor or an original joint inventor of a claimed invention in

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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UMCD-2020-0279 102883-US-PA

DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

- 2 -

Signature:_	Ohia Jung Hou	∖ Date:	-⊬ 1 G 2020

Legal Name of Sole or First Inventor: Chia-Jung Hsu

Residence: Tainan City, Taiwan

Mailing Address: 13F.-2, No. 10, Luyuan 2nd St., Xinshi Dist., Tainan City 744, Taiwan (R.O.C.)

Signature:	Chin	- Hung	Chen	Date:	SEP	16	2020	
Legal Name o	of Additional	Joint Inventor,	if any: Chin-Hung					
Residence: T	ainan City, T	Γaiwan						
Mailing Addre	ess: 12F6,	No. 199, Dongo	qiao 7th Rd., Yong	kang Dist., Tai	inan City	710,	Taiwan	
	(R.O.C.	.)						

		SEP 1 0 2020
Signature: Chun-Ya Chiu	Date:	SEP 1 o 2020

Legal Name of Additional Joint Inventor, if any: Chun-Ya Chiu

Residence: Tainan City, Taiwan

Mailing Address: 9F.-1, No. 151, Xing'an St., Shanhua Dist., Tainan City 741, Taiwan (R.O.C.)

Signature: (Mi	h - 1	Eai	Hsu	Date:	SEP	16	2020

Legal Name of Additional Joint Inventor, if any: Chih-Kai Hsu

Residence: Tainan City, Taiwan

Mailing Address: No. 8, Aly. 80, Ln. 168, Sec. 1, Fuqiang Rd., Yongkang Dist., Tainan City 710,

Taiwan (R.O.C.)

Signature: SSU - I FU	Date:	SEP 1 6 2020
Legal Name of Additional Joint Inventor, if any: Ssu-I Fu		
Residence: Kaohsiung City, Taiwan		
Mailing Address: No.48-2, Yuliao Rd., Qiaotou Dist., Kaoh	siung City 825, Ta	aiwan (R.O.C.)

Signature: Jsai-Yu Weh	Date:	SEP	167	2020
Legal Name of Additional Joint Inventor, if any: Tsai-Yu Wen	1			
Residence: Tainan City, Taiwan				
Mailing Address: No.1, Aly. 55, Ln. 31, Daqiao 1st St., Yongk	ang Dist., Ta	ainan Cil	ty 710,	Taiwan
(R O C)				

Signature:	Shi	Tou	Giv		Date:	SEP	16	2020
Legal Name of Additional Joint Inventor, if any: Shi You Liu								
Residence: Kaohsiung City, Taiwan								
Mailing Address: No. 108, Heping Rd., Hunei Dist., Kaohsiung City 829, Taiwan (R.O.C.)								

Signature:	m-Hstang	Lin		Date:	SEP	16	2020
	dditional Joint Invento		u-Hsiang Lin				
Residence: New	Taipei City, Taiwan						
Mailing Address:	2F., No.5-1, Ln. 165,	Zhonghe F	Rd., Zhonghe Di	st., New	Taipei C	City 23	5, Taiwan
	(R.O.C.)						